

# *E&E Industry V5R12 Sales Solutions*



**Yannick Wittner, Dassault Systemes**

**Jim Denzak , IBM**

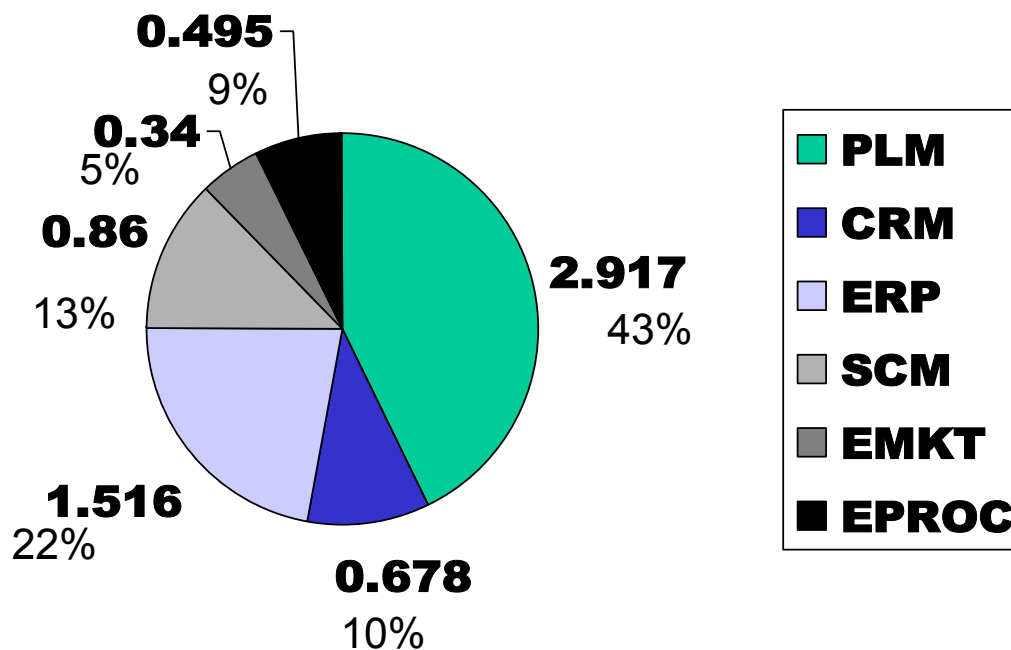


Version 5 Release 12  
October 2003  
V512\_E&E sales



# 2003 Solution Opportunity

Total Opportunity: \$6.8B\*



\* Electronics industry

# Our current PLM 'Sweet Spots'

.....from what our customers are telling us

**"We need a controlled place to easily store & retrieve all of the product information to enable consistency and reduce delays"**

## Collaborative PLM Hub

- *centred around SMARTEAM*
- *R12 considerably strengthened with enhanced network supply chain integration (methodology), better accesibility and security (role management support), faster and easier integration with usual reporting applications (oledb support), integration with enterprise application framework ( Websphere integration)*

**"The mechanical design solution should enable product innovation"**

## Product innovation authoring

- *centred around CATIA and SMARTEAM*
- *R12 enhances detailed design, sheetmetal and drafting applications, brings technological breakthrough to mold design (Functional Molded Part).*

# Our value proposition

## “Collaborative PLM Hub”




### Simplify design cycle and introduction to manufacturing

- 👤 Controlled product information access for dispersed users
  - 👉 *Right data, right place, right time*
- 👤 Energise and link the new product introduction project team across the extended enterprise
  - 👉 *Common view of the total product, manage change, collaborate to close BOM costing early*
- 👤 Easier definition of new product variants
  - 👉 *Faster approval of new parts, project and product morphing, suppliers involved early*
- 👤 More efficient and integrated project management

# Our value proposition

## **“Product Innovation Authoring”**

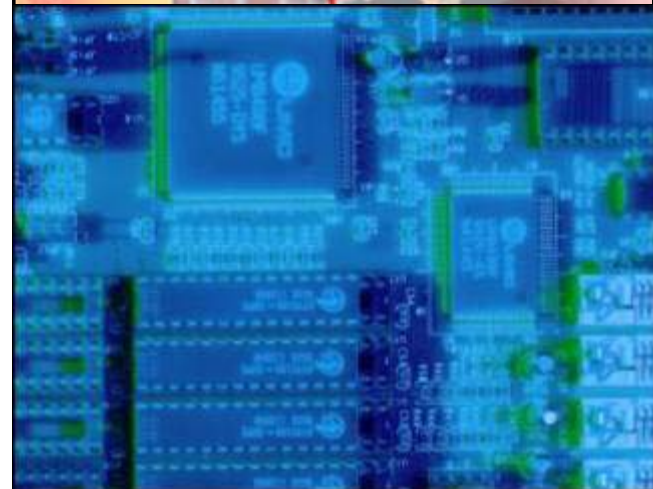
**Enable your customers to innovate and reduce delays in new product introduction by effective & integrated processes**

-  Drive down 'time to market' by exploiting concurrent engineering
-  Meet market goals through 'late changes' to styling or internal packaging
-  Close key design studies faster through cross-discipline decision making



# Our PLM Best Practices Offerings

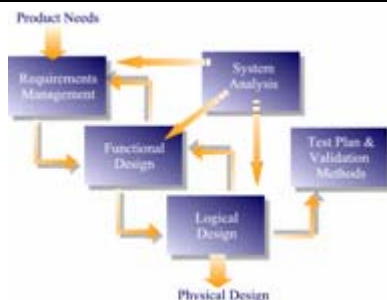
- Collaborative System Engineering for Electronics
- Program & Project Management
- Integrated Mechanical Product Development



# Collaborative System Engineering for Electronics

*A strategic solution enabling companies to drive their end-to-end product development process from needs identification to final product validation.*

- Requirements Management
- Functional Design
- Logical Design
- Test Plan and Validation Methods



- Pain 1 : Difficulty in finding optimal product function/cost tradeoff**
  - Optimize the tradeoff by supporting a comprehensive product definition process
- Pain 2 : Difficulty in identifying and controlling key product success factors**
  - Manage early product definition stage (where 80% of total product cost are committed)
- Pain 3 : Lack of integration between product requirements and design**
  - Unify requirements management with functional, logical and physical product design processes
- Pain 4 : Difficulty in complying with stringent and complex industry regulations**
  - Identify impact of regulation on product definition and control test and validation procedures
- Pain 5 : Lack of coordination between supply chain actors**
  - Optimize supply chain collaboration based on single unified product definition
- Pain 6 : Low reuse of corporate knowledge**
  - Standardize product architecture to foster increased re-use of corporate assets



## Reference Customers and Wins:



## PLM Portfolio :

- ✓ SMARTeam P1 Configuration :
- ✓ SET, SNV





# Collaborative System Engineering for Electronics

## Best Practices Portfolio



**Requirements Management**



**Functional Analysis & System Architecture Definition**



**Classified Engineering Catalogs**



**Project Management and Derivation**



**Collaborative workspace for Electronics**





# Collaborative System Engineering for Electronics

## Sales Pocket Card

### Targets



US SIC codes :

3661,3663,3669,3812,3571,3572,3575,3577,3578,3579,3695,3596,3822,3824,3825,  
3826,3829,3612,3613,3699,3827,3842,3844,3845,3851,3821,3841,3843,3651,3652,3861

### Customers References / Wins :



Recommended Solutions :  
SMARTTEAM P1 Configuration :  
SET, SNV

### More information :

✓ Laurent CHERPRENET (DS) : [lcj@ds-fr.com](mailto:lcj@ds-fr.com)



### Pains and Value Proposal:

**Pain 1 : Difficulty in finding optimal product function/cost tradeoff**

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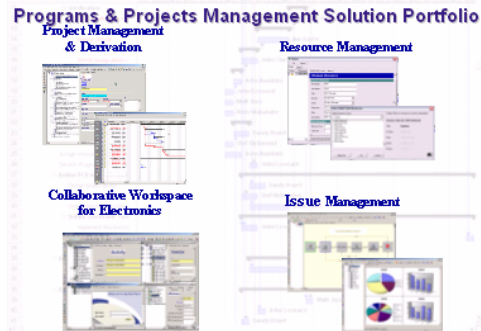


# Program & Project Management

*Organize, Execute, Control and Resolve your Projects*

## Connect all Project related Information :

- 👤 Scope, Schedule, Resources, risks and issues
- 👤 Stakeholders with their different needs and expectations
- 👤 Identified Requirements



## Pain 1: Fragmented Information from various environments

- 👤 Business processes and project management information integration

## Pain 2 : Lack of knowledge re-use

- 👤 Project standardization and re-use

## Pain 3 : Inconsistent project information sharing across teams

- 👤 Integration of dispersed project teams

## Pain 4 : Lack of projects visibility, forecast and traceability

- 👤 Project monitoring and dashboarding



## Reference Customers and Wins:

**CORECESS**



The ASE Group

**COMVERSE**  
inspire · create · express

## PLM Portfolio :

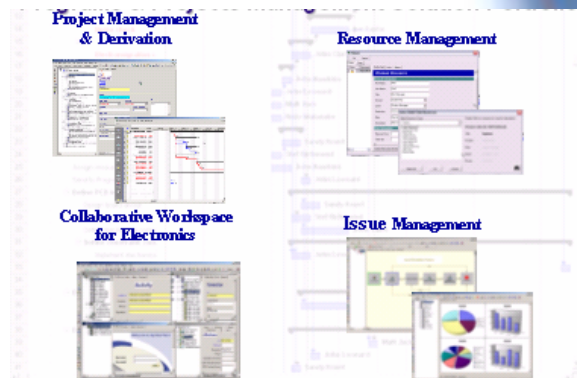
✓ Smarteam Editor Configuration, SmartWeb Editor Configuration

# Program & Project Management

## Best Practices Portfolio



- Project Management & Derivation
- Issue Management
- Resource Management
- Collaborative workspace for Electronics



# Program & Project Management

## Sales Pocket Card

### Targets



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### More information :

✓ Thierry GRISET (DS) : [tgt@ds-fr.com](mailto:tgt@ds-fr.com)



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# Integrated Mechanical Product Development

*Fostering Innovation, Speeding up Development*

## Scope :

- Speeding up EE product development through re-use of designs and knowledge and through an efficient collaboration between disciplines and applications.



## Pain 1: Slow Style to Detailed Design Loops

- Fast design possibilities exploration through associativity and applications integration

## Pain 2 : Disposable Product Design

- High level of re-use through relational design & templates

## Pain 3 : Design/Manufacturing Mismatches

- Design/Manufacturing consistency through integrated mold creation applications and use of know-how holding templates

## Pain 4 : Mechanical/Electronics Miscommunication

- Consistent and even synchronized mechanical & electronics processes through common data base and PDM system customization.

## Pain 5 : Slow Simulation & Analysis Processes Loops

- Fast analysis & review process through applications integration



## Reference Customers and Wins:

**National/Panasonic**

**Electrolux**



**Clarion**

**PELTOR**

**SONY**

## PLM Portfolio :

### ✓ P2 Configuration :

- ✓ YM2, SA2, DPS, TDM, SET, SCT

### ✓ P2 Add-On :

- ✓ CBD, GDY, SMD, CCV, MTD, MSC V5, CTH

# Integrated Mechanical Product Development Solution (IMPD)

## Best Practices Portfolio

**Specification driven  
Product Morphing**



**Embedded Know-how  
Component Morphing**



**Plastic from Design  
to Generative Molding  
and Tooling**



**Sheet Metal Design  
for Manufacturing**



**Industrial Design**

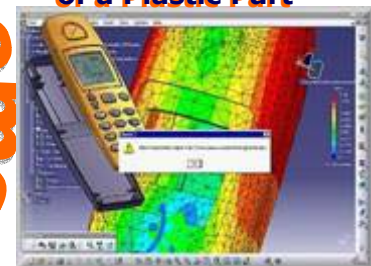


**Technology Survey**

**Collaborative Workspace  
For Electronics**



**Structural Analysis  
of a Plastic Part**



**Decision Management  
Design Review**

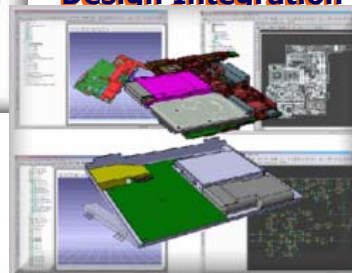


Vendors

EMS

**Quality Management**

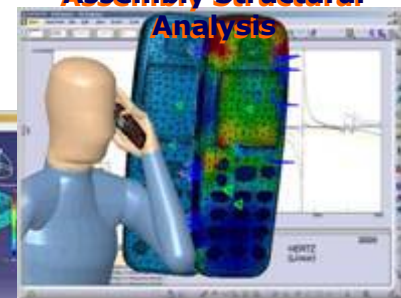
**Electronic & Mechanical  
Design Integration**



**Thermal Analysis  
Of a PCB**



**Generative Core Mobile  
Assembly Structural  
Analysis**



# Integrated Mechanical Product Development

## Sales Pocket Card

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### Customers References / Wins :

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**clarion**



**PELTOR**

### Recommended Solutions :

- ✓ P2 Configuration :
  - ✓ YM2, SA2, DPS, TDM, SET, SCT
- ✓ P2 Add-On :
  - ✓ CBD, GDY, SMD, CCV, MTD + MSC V5i GTH

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